CLEAN VERSION OF NEW CLAIMS

Claim 27. An optical integrated circuit, comprising:

a substrate;

a plurality of mirror sub-arrays; and

means attached to a top layer of the substrate for aligning the plurality of mirror sub-arrays during placement of the plurality of mirror sub-arrays.

Claim 28. The optical integrated circuit of Claim 27, wherein the means is a template layer having rectangular apertures for receiving the plurality of mirror sub-arrays.

Claim 29. The optical integrated circuit of Claim 27, wherein the means has protrusions perpendicular to the mounting surface of the substrate for guiding the plurality of mirror sub-arrays during placement.

Claim 30. The optical integrated circuit of Claim 29, wherein the protrusions are tapered, having a narrow end farthest from the substrate, so that the mirror sub-arrays are guided toward the substrate.

Claim 31. The optical integrated circuit of Claim 30, wherein the means has rectangular apertures for accepting the plurality of mirror sub-arrays, and wherein walls of the rectangular apertures are formed by the protrusions.

Claim 32. The optical integrated circuit of Claim 27, further comprising an adhesive layer for attaching the plurality of mirror sub-arrays to the substrate.

Claim 33. The optical integrated circuit of Claim 32, wherein the adhesive layer is cut to provide vents to permit the escape of gas during mounting of the plurality of mirror sub-arrays.

Claim 34. The optical integrated circuit of Claim 27, wherein the substrate has perforations for permitting the escape of gas during mounting of the plurality of mirror sub-arrays.

Claim 35. The optical integrated circuit of Claim 27, wherein the means is bonded to the substrate by an eutectoid layer.

Claim 36. The optical integrated circuit of Claim 27, wherein the means is an epitaxially grown semiconductor layer.

Claim 37. The optical integrated circuit of Claim 27, wherein the means is an etched metal layer.

Claim 38. The optical integrated circuit of Claim 27, wherein the means is a stamped metal layer.